Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138								
PRODUCT/PROCESS CHANGE NOTICE (PCN)								
PCN #: A1810-01 Date: November Product Affected: ASI4UE-E-G1-SR, ASI4UE-E	·	MEANS OF DISTI □ Product Mark ■ Back Mark □ Date Code	NGUISHING CHANGED DEVICES: Lot # will have a "GR" prefix					
Date Effective: February 7, 2019		□ Other						
Contact: IDT PCN DESK		Attachment:	Yes No					
E-mail: pcndesk@idt.com		Samples:	Please contact your local sales representative for sample request & availability.					
DESCRIPTION AND PURPOSE OF CHANGE:								
 Die Technology Wafer Fabrication Process Assembly Process This notification is to advise our customers that IDT is transferring assembly location of select products from Amkor Philippines to Greatek, Taiwan as a result of Amkor discontinuing the assembly process of these products. 								
□ Equipment ■ Material	Greatek is curre	ently a qualified IDT	Subcontractor.					
□ Testing	TI ' ohoo		6					
- Manufacturing Site	There is no chai	nge to the moisture p	erformance rating.					
□ Data Sheet III Dother IIII	Please refer to A	Attachment 1 for the	qualification summary and material set details.					
DEI IARII ITV/OUAL IEICATION SUMMARY	7.							
	RELIABILITY/QUALIFICATION SUMMARY: Qualification has been successfully completed. There is no change in MSL rating.							
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.								
Customer:		oval for shipmen	ts prior to effective date.					
Name/Date:	E-Mail Addres	ss:						
Title:	Phone# /Fax# :	:						
CUSTOMER COMMENTS:								
IDT ACKNOWLEDGMENT OF RECEIPT:								
RECD. BY:	DA	ATE						



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ATTACHMENT 1 - PCN # : A1810-01

PCN Type: Change of Assembly Location & Assembly Material Sets

Data Sheet Change: N/A

Detail Of Change:

This notification is to advise our customers that IDT is transferring assembly location of select products from Amkor Philippines to Greatek, Taiwan as a result of Amkor discontinuing the assembly process of these products.

Greatek is currently a qualified IDT Subcontractor.

There is no change in form, fit and function of the products including RoHS compliance and MSL rating.

SOIC-28: Qualified Material Sets, by Assembly Subcontractor

	Existing Assembly	New Assembly	
Material Set / Assembly	ATP - Amkor, Philippines	GEI - Greatek, Taiwan	
Die Attach	Ablestik 8290	CRM-1076DJ-G	
Bonding Wire	Gold wire	Gold wire	
Mold Compound	EME-G600	EME-G700	



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Qualification Information and Qualification Data:

Affected Packages:	SOIC-28
Assembly Material:	The affected package type is using the respective subcon standard materials as shown on page 1 of this attachment. Qualification testing was completed on the worse case package.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests

		Test Results (Rej/SS)			
Test Description	Test Method	Lot 1	Lot 2	Lot 3	
¹ HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A102	0 / 25	0/25	0 / 25	
¹ Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0 / 25	0/25	0 / 25	
High Temperature Storage Test (150°C, 1000 hours)	JESD22-A103	0 / 45	-	-	
Physical Dimensions	JESD22- B100/B108	0 / 10	0 / 10	0 / 10	
Wire Bond Shear	AEC Q100-001	0 / 5	-	-	
Wire Bond Pull	MIL883 M2011	0 / 5	_	_	

Oualification Vehicle: SOIC-28 (3 lots)

Notes: 1. HAST and Temperature Cycle were subjected to Preconditioning per JESD22-A113 for MSL 3.